# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

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|---|---|
| **1.1 Company** | STMicroelectronics International N.V |
| **1.2 PCN No.** | EMBEDDED PROCESSING/26/15869 |
| **1.3 Title of PCN** | STM32H562x, STM32H563x and STM32H573x - product enhancement |
| **1.4 Product Category** | STM32H562x ,<br>STM32H563x and<br>STM32H573x |
| **1.5 Issue date** | 2026-02-05 |

## 2. PCN Team

| | |
|---|---|
| **2.1 Contact supplier** | |
| **2.1.1 Name** | PIKE EMMA |
| **2.1.2 Phone** | +44 1628896111 |
| **2.1.3 Email** | emma.pike@st.com |
| **2.2 Change responsibility** | |
| **2.2.1 Product Manager** | Patrick AIDOUNE |
| **2.1.2 Marketing Manager** | Marie TOURNUT |
| **2.1.3 Quality Manager** | Pascal NARCHE |

## 3. Change

| **3.1 Category** | **3.2 Type of change** | **3.3 Manufacturing Location** |
|---|---|---|
| General Product & Design | Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix | ST Crolles 300 (France) |

## 4. Description of change

| | **Old** | **New** |
|---|---|---|
| **4.1 Description** | Current STM32H562x, STM32H563x and STM32H573 (Revision X) products and System Flash Security Package (SFSP) have limitations as described in Errata Sheet ES0565 - Rev 6 - March 2025 | STM32H562x, STM32H563x and STM32H573 (Revision W) products & System Flash Security Package (SFSP) enhancement.<br><br>Change of security descriptor located on Bootloader area needed for integration w/ SFSP :<br>- The change of the SFSP descriptor located in Bootloader area has no impact on Bootloader.<br>- The Bootloader binary remains unchanged.<br>- Changes done in SFSP descriptor: change the address in API table for RSS services.<br><br>ES0565 device Errata sheet:<br>- New Rev. 8 (replacing Rev. 7).<br><br>AN6014 SFSP Application Note:<br>- New SFSP version v2.7.0 (replacing the v2.6.0).<br><br>AN2606 application Note :<br>- New Revision 70 (replacing Rev 69).<br>- New Bootloader version V14.5 (replacing V14.4). |
| **4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?** | Functionality enhancement | |

## 5. Reason / motivation for change

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| **5.1 Motivation** | Improvements implemented to fix bugs. |
| **5.2 Customer Benefit** | SERVICE CONTINUITY |

## 6. Marking of parts / traceability of change

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|---|---|
| **6.1 Description** | Traceability ensured by ST internal tools.<br>Die revision changes from "X" to "W" on Package Marking |

### 7. Timing / schedule

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|---|---|
| **7.1 Date of qualification results** | 2026-03-05 |
| **7.2 Intended start of delivery** | 2026-03-05 |
| **7.3 Qualification sample available?** | Upon Request |

### 8. Qualification / Validation

| | | | |
|---|---|---|---|
| **8.1 Description** | 15869 PCN15869 RERMCD2111_STM32H5 - Die 484_W cut2.4 - qual plan.pdf | | |
| **8.2 Qualification report and qualification results** | Available (see attachment) | **Issue Date** | 2026-02-05 |

### 9. Attachments (additional documentations)

15869 Public product.pdf
15869 PCN15869 RERMCD2111_STM32H5 - Die 484_W cut2.4 - qual plan.pdf
15869 _Additional information.pdf

### 10. Affected parts

| **10. 1 Current** | | **10.2 New (if applicable)** |
|---|---|---|
| **10.1.1 Customer Part No** | **10.1.2 Supplier Part No** | **10.1.2 Supplier Part No** |
| | STM32H562AGI6 | |
| | STM32H562AII6 | |
| | STM32H562IGK6 | |
| | STM32H562IGT6 | |
| | STM32H562IIK6 | |
| | STM32H562IIT6 | |
| | STM32H562RGT6 | |
| | STM32H562RGV6 | |
| | STM32H562RIT6 | |
| | STM32H562RIV6 | |
| | STM32H562VGT6 | |
| | STM32H562VIT6 | |
| | STM32H562ZGT6 | |
| | STM32H562ZIT6 | |
| | STM32H563AGI6 | |
| | STM32H563AII3Q | |
| | STM32H563AII6 | |
| | STM32H563IGK6 | |
| | STM32H563IGT6 | |
| | STM32H563IIK3Q | |
| | STM32H563IIK6 | |
| | STM32H563IIT3Q | |
| | STM32H563IIT6 | |
| | STM32H563RGT6 | |
| | STM32H563RGV6 | |
| | STM32H563RIT6 | |
| | STM32H563RIV6 | |
| | STM32H563VGT6 | |
| | STM32H563VIT3Q | |
| | STM32H563VIT6 | |
| | STM32H563ZGT6 | |
| | STM32H563ZIT3Q | |
| | STM32H563ZIT6 | |
| | STM32H573AII3Q | |

| | | |
|---|---|---|
| | STM32H573AII6 | |
| | STM32H573IIK3Q | |
| | STM32H573IIK6 | |
| | STM32H573IIT3Q | |
| | STM32H573IIT6 | |
| | STM32H573RIT6 | |
| | STM32H573RIV6 | |
| | STM32H573VIT3Q | |
| | STM32H573VIT6 | |
| | STM32H573ZIT3Q | |
| | STM32H573ZIT6 | |

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